

AMENDMENTS TO THE SPECIFICATION

Please replace the following paragraph(s):

Page 7, line 17 to page 8, line 8:

In accordance with one embodiment of the present invention, processor 100 and voltage regulator 150 of Figure 1 may be implemented as processor 210 and voltage regulator 215 of Figure 2B. Voltage regulator 215 provides a supply voltage, Vcc(global), to processor 210 via one or more voltage/power supply lines that couple voltage regulator 215 to one or more supply voltage input ports of processor 210. ~~Processor 200~~ Processor 210 includes a local voltage regulator 211 coupled to one or more supply voltage input ports of processor 210 to receive Vcc(global). Voltage regulator 211 may be powered by Vcc(global) and provides a local supply voltage Vcc(local) for the processor. This Vcc(local) may be distributed to various circuits of processor 210 to power the circuits. In addition, Vcc(global) may also be distributed to various circuits of processor 210 to power the circuits. For example, Vcc(local) may be used to power all or a portion of a core of processor 210, and Vcc(global) may be used to power all or a portion of an input/output ring of processor 210. In accordance with one embodiment of the present invention, Vcc(local) may be less than Vcc(global).

Page 9, lines 1-9:

Voltage regulator 211 of Figure 2B may be designed using one or more op amps, comparators, or switching regulators that may include analog circuits

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integrated with the digital circuitry of ~~processor 200~~ processor 210 together on the same semiconductor substrate. An op amp of voltage regulator 211 may be designed as described below in conjunction with Figure 3B. In accordance with one embodiment of the present invention, multiple voltage regulators may be integrated on the same semiconductor substrate as the processor. For another embodiment of the present invention, one or more voltage regulators may be integrated with one or more voltage sensors on the same semiconductor substrate as the processor.

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